



Schedule of Scope to Certificate of Approval Component Capability Approval

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Manufacturer: Merlin Artetch Ltd

Board Types: Rigid Multi-layer BS CECC 23300-003
Rigid double-sided with plated through holes BS CECC 23200-003
Rigid single and double-sided with plain holes BS CECC 23100-003

Base Materials: Epoxide Woven Glass

Board Size: 401 mm x 366 mm Maximum

Conductors: Minimum Width: 150 μm ± 50 μm
Minimum Spacing: 150 μm ± 50 μm

Number of Layers: 24 Maximum

Plated-through Hole Diameter: 0.4 mm Minimum finished for component mounting
0.5 mm Minimum drilled via hole

Aspect Ratio: 7.6 : 1 Maximum

Finishes:

- * Hot Air Solder Levelling
- * Immersion Silver
- * 2.5 μm Gold over Copper Edge Contacts
- Liquid Photoimagable Solder Resist
- Dry Film Solder Resist
- Notation Ink

* These finishes meet the solderability requirements of IEC 60326-2; Test Methods 14a and 20a.

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